

What is claimed is:

1. An embedding resin comprising a thermoplastic resin, an acid anhydride curing agent, a curing accelerator, and a filler, wherein the embedding resin shows a viscosity  
5 of not higher than 85 Pa • s in a shear rate of 8.4 s<sup>-1</sup> after allowing to stand for 24 hours at 25°C ± 1°C.

2. The embedding resin according to claim 1, wherein the acid anhydride curing agent has a viscosity at 25°C ± 1°C  
10 of not higher than 170 mPa • s.

3. The embedding resin according to claim 1, which contains the filler in an amount of from 51% by weight to 74% by weight.  
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4. The embedding resin according to claim 1, wherein the filler contains at least one inorganic filler.

*Sub* 5. A wiring substrate comprising: an insulating  
20 substrate having an opening; at least one electronic part disposed in the opening; and an embedding resin according to claim 1, wherein the at least one electronic part is embedded with the embedding resin.

6. A wiring substrate comprising: a core substrate;  
and a build-up layer provided on at least one side of the core  
substrate and formed by alternately laminating an insulating  
layer and a wiring layer, wherein at least one of the core  
substrate and the building-up layer has an opening  
penetrating therethrough, and an electronic part is disposed  
in the opening and embedded with an embedding resin according  
to claim 1.

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